

CHO-BOND 360-20

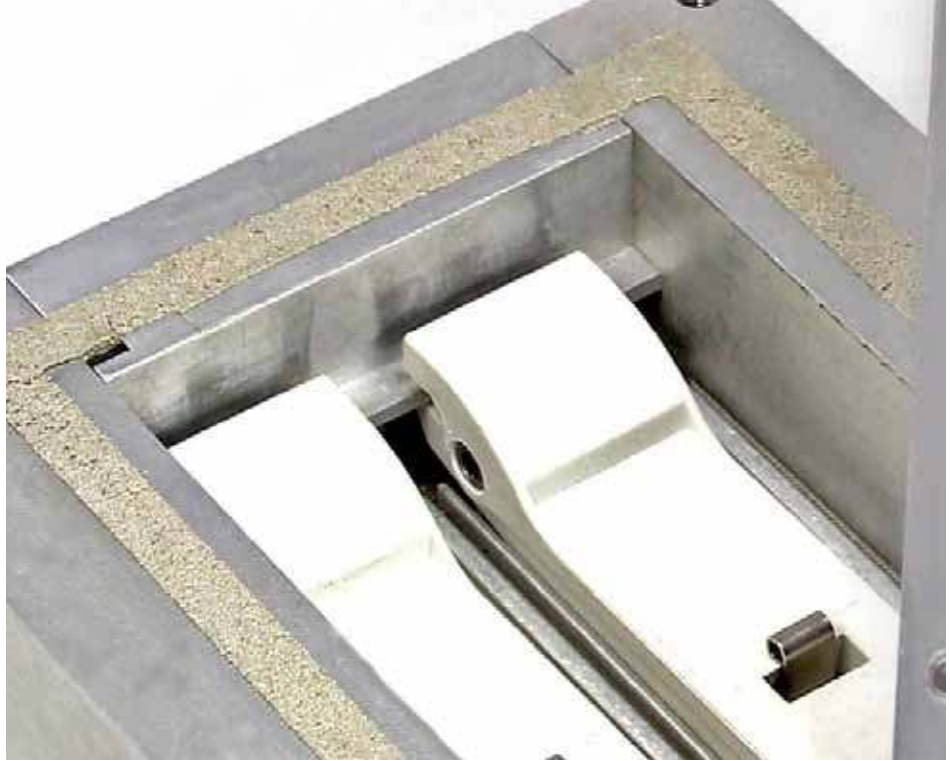
TWO COMPONENT GENERAL PURPOSE ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE

CHO-BOND 360-20 is a two-component, silver plated copper filled conductive epoxy adhesive designed for applications where a strong, conductive electrical bond must be achieved. The silver copper filler of CHO-BOND 360-20 provides a cost effective alternative to pure silver filled conductive epoxies in applications where moderate conductivity is acceptable. This thick paste is good for filling rather large bond lines and cracks (0.004 inches -0.025 inches) of electrical boxes and enclosures. It is recommended as a thermo-setting EMI/RFI shielding compound and is effective even for designs requiring the use of a fillet as opposed to a flanged bead.

Applications also include sealing EMI / RFI leaks around vents, windows and machined surfaces, the bonding environmental sealing, and EMI shielding of cast aluminium housings; the bonding and shielding of conduit bulkhead passthroughs.

Where galvanic potential with the substrates exists, such as with zinc or aluminium, be sure to overcoat the cured fillet with an electrically insulating epoxy silicone, polyurethane or polysulfide moisture vapour barrier.

Curing of CHO-BOND 360-20 can be achieved in as little as 15 minutes with heat to minimize equipment downtime and increase manufacturing throughput. The 1:1 weight mix ratio makes CHO-BOND 360-20 easy to handle and use.



Features and Benefits:

Minimal shrinkage, no ventilation required.

No VOC's

Fast heat cure, increases throughput and minimises equipment downtime.

60 minute working life, works over a wide temperature range, good chemical resistance >1600 psi lap shear.

Good for permanent bonding.

Thick paste, good for large cracks and voids (>0.25 in). Can be used on overhead or vertical surfaces.

Two component.

Epoxy.

Low cost (£/cc), good conductivity 0.005 ohm-cm.

CHO-BOND 360-20 - Product Information

Table 1 Typical Properties

CHO-BOND 360-20		
Typical Properties	Typical Values	Test Method
Polymer	Epoxy	N/A
Filler	Silver-Plated Copper	N/A
Mix Ratio, A : B (by weight)	1 : 1	N/A
Colour	Light Gray	N/A (Q)
Consistency	Gritty Paste	N/A (Q)
Maximum DC Volume Resistivity (Cure Cycle 1)	0.005 ohm-cm	CHO-95-40-5101* (Q/C)
Minimum Lap Shear Strength (Cure Cycle 1)	1600 psi (11,032 kPa)	CHO-95-40-5300* (Q/C)
Specific Gravity (Room Temp Cure)	5.0	ASTM D792 (Q/C)
Hardness (Cure Cycle 1)	80 Shore D	ASTM-D2240 (Q)
Continuous Use Temperature	- 62°C to 100°C (-80 °F to 212 °F)	N/A (Q)
Elevated Temperature Cure Cycle	Cure Cycle Option 1: 0.25 hours @ 115°C (235°F) Cure Cycle Option 2: 2.0 hours @ 66°C (150°F)	N/A
Room Temperature Cure	24 hours	N/A (Q)
Working Life	1.0 hour	N/A (Q)
Shelf Life, unopened	9 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.010 in (0.25 mm)	N/A
Maximum thickness recommended	None	N/A
Volatile Organic Content (VOC)	0 g/l	Calculated
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	5,500 in ² (35,484 cm ²)	N/A

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

* This test Method is available from Parker Chomerics.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 360-20	85	2 component, 1/2 pint aluminium can kit	50-00-0360-0020	Not Required
	454	2 component, 1 pint aluminium can kit	50-01-0360-0020	Not Required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.



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www.hitek-ltd.co.uk
 +44 (0)1724 851678



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